

Inventor Name Search Result

Your Search was:

Last Name = SEZI

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Application#	Patent#	Status	Date Filed	Title	Inventor Name 51
<u>10670663</u>	Not Issued	020	09/25/2003	METHOD OF PRODUCING AN ADHESIVE BOND	SEZI, RECAI
<u>10631587</u>	Not Issued	030	07/31/2003	MICROELECTRONIC PROCESS AND STRUCTURE	SEZI, RECAI
<u>10609460</u>	Not Issued	030	06/27/2003	POLY-O-HYDROXYAMIDE, POLYBENZOXAZOLE, AND ELECTRONIC COMPONENT INCLUDING A DIELECTRIC HAVING A BARRIER EFFECT AGAINST COPPER DIFFUSION, AND PROCESSES FOR PREPARING POLY-O-HYDROXYAMIDES, POLYBENZOXAZOLES, AND ELECTRONIC COMPONENTS	SEZI, RECAI
<u>10609456</u>	Not Issued	030	06/27/2003	BIS-O-AMINOPHENOLS AND PROCESSES FOR PRODUCING BIS-O-AMINOPHENOLS	SEZI, RECAI
<u>10609453</u>	Not Issued	020	06/27/2003	POLY-O-HYDROXYAMIDE, POLYBENZOXAZOLE FROM THE POLY-O-HYDROXYAMIDE, ELECTRONIC COMPONENT INCLUDING A POLYBENZOXAZOLE, AND PROCESSES FOR PRODUCING THE SAME	SEZI, RECAI
<u>10472772</u>	Not Issued	030	02/10/2004	COATING MATERIAL FOR ELECTRONIC COMPONENTS	SEZI, RECAI
<u>10424376</u>	Not Issued	020	04/28/2003	METHODS FOR PRODUCING A DIELECTRIC, DIELECTRIC HAVING SELF-GENERATING PORES, MONOMER FOR POROUS DIELECTRICS, PROCESS FOR PREPARING POLY-O-HYDROXYAMIDES, PROCESS FOR PREPARING POLYBENZOXAZOLES, AND	SEZI, RECAI

				PROCESSES FOR PRODUCING AN ELECTRONIC COMPONENT	
<u>10261034</u>	Not Issued	040	09/30/2002	POLY-O-HYDROXYAMIDES, POLYBENZOXAZOLES, PROCESSES FOR PRODUCING POLY-O-HYDROXYAMIDES, PROCESSES FOR PRODUCING POLYBENZOXAZOLES, DIELECTRICS INCLUDING A POLYBENZOXAZOLE, ELECTRONIC COMPONENTS INCLUDING THE DIELECTRICS, AND PROCESSES FOR MANUFACTURING THE ELECTRONIC COMPONENTS	SEZI, RECAI
<u>10244839</u>	Not Issued	071	09/16/2002	BIS-O-AMINOPHENOL DERIVATIVES, POLY-O-HYDROXYAMIDES, AND POLYBENZOXAZOLES, USABLE IN PHOTSENSITIVE COMPOSITIONS, DIELECTRICS, BUFFER COATINGS, AND MICROELECTRONICS	SEZI, RECAI
<u>10244802</u>	Not Issued	030	09/16/2002	POLYBENZOXAZOLES FROM POLY-O-HYDROXYAMIDE, NOVEL POLY-O-HYDROXYAMIDES, PREPARATION PROCESSES THEREFOR, AND THEIR APPLICATION IN MICROELECTRONICS	SEZI, RECAI
<u>10244301</u>	Not Issued	041	09/16/2002	BIS-O-NITROPHENOLS DERIVATIVES AND POLY-O-HYDROXYAMIDES, POLYBENZOXAZOLES, MATERIALS, AND MICROELECTRONIC DEVICES MADE THEREFROM	SEZI, RECAI
<u>10244280</u>	Not Issued	030	09/16/2002	PHOTSENSITIVE FORMULATION FOR BUFFER COATINGS, FILM INCLUDING THE FORMULATION, AND METHOD FOR MANUFACTURING ELECTRONICS USING THE FORMULATION	SEZI, RECAI
<u>10244257</u>	Not Issued	030	09/16/2002	PHOTSENSITIVE FORMULATION FOR BUFFER COATINGS, FILM CONTAINING THE PHOTSENSITIVE FORMULATION, AND METHOD FOR FABRICATING ELECTRONICS WITH THE PHOTSENSITIVE FORMULATION	SEZI, RECAI
<u>10208422</u>	Not	092	07/30/2002	ADHESIVELY BONDED CHIP-AND	SEZI,

	Issued			WAFER STACKS	RECAI
<u>10208397</u>	Not Issued	071	07/30/2002	USE OF POLYBENZOXAZOLES (PBOS) FOR ADHESION	SEZI, RECAI
<u>10206505</u>	Not Issued	071	07/26/2002	PHENYL-LINKED OXAZOLE CYANATES AS DIELECTRICS HAVING GOOD ADHESIVE AND FILLING PROPERTIES	SEZI, RECAI
<u>10187017</u>	Not Issued	093	07/01/2002	PHOTO-CROSS-LINKABLE POLYMERS, METHOD OF PRODUCING A CROSS-LINKED POLYMER, CROSS-LINKED POLYMER, AND CROSS-LINKED POLYMER COATING	SEZI, RECAI
<u>10180438</u>	Not Issued	071	06/26/2002	COMPOSITION AND PROCESS FOR THE PRODUCTION OF A POROUS LAYER USING THE COMPOSITION	SEZI, RECAI
<u>10156484</u>	<u>6635410</u>	150	05/28/2002	METALLIZING METHOD FOR DIELECTRICS	SEZI, RECAI
<u>10154297</u>	Not Issued	061	05/23/2002	ANTIREFLECTIVE, LAYER-FORMING COMPOSITION, LAYER CONFIGURATION CONTAINING THE ANTIREFLECTIVE LAYER, AND PROCESS FOR PRODUCING THE ANTIREFLECTIVE LAYER	SEZI, RECAI
<u>10145393</u>	Not Issued	030	05/14/2002	WIRING PROCESS	SEZI, RECAI
<u>10098845</u>	Not Issued	040	03/14/2002	METHOD FOR PRODUCING A POROUS COATING	SEZI, RECAI
<u>10008796</u>	Not Issued	090	11/13/2001	POLYBENZOXAZOLE PRECURSORS, PHOTORESIST SOLUTION, POLYBENZOXAZOLE, AND PROCESS FOR PREPARING A POLYBENZOXAZOLE PRECURSOR	SEZI, RECAI
<u>09901218</u>	<u>6437178</u>	150	07/09/2001	O-AMINOPHENOLCARBOXYLIC ACID AND O-AMINOTHIOPHENOLCARBOXYLIC ACID	SEZI, RECAI
<u>09817967</u>	Not Issued	041	03/27/2001	COMPONENT HAVING AT LEAST TWO MUTUALLY ADJACENT INSULATING LAYERS AND CORRESPONDING PRODUCTION METHOD	SEZI, RECAI
<u>09817966</u>	Not Issued	161	03/27/2001	PROCESS FOR METALLIZING AT LEAST ONE INSULATING LAYER OF A COMPONENT	SEZI, RECAI
<u>09817963</u>	Not Issued	071	03/27/2001	METHOD FOR THE METALIZATION OF AN INSULATOR AND/OR A	SEZI, RECAI

				DIELECTRIC	
<u>09803762</u>	<u>6531632</u>	150	03/12/2001	BIS-O-AMINOPHENOLS AND O-AMINOPHENOLCARBOXYLIC ACIDS AND PROCESS FOR PREPARING THE SAME	SEZI, RECAI
<u>09509598</u>	Not Issued	161	03/29/2000	SEMICONDUCTOR COMPONENT AND METHOD FOR THE PRODUCTION THEREOF	SEZI, RECAI
<u>08934448</u>	<u>6037043</u>	150	09/19/1997	UV-HARDENABLE AND THERMALLY HARDENABLE EPOXY RESINS FOR UNDERFILLING ELECTRICAL AND ELECTRONIC COMPONENTS	SEZI , RECAI
<u>08705575</u>	<u>5783654</u>	150	08/29/1996	PREPARATION OF POLY-O-HYDROXYMIDES AND POLY O-MERCAPTOAMIDES	SEZI , RECAI
<u>08705469</u>	<u>5696218</u>	150	08/29/1996	PREPARATION OF POLY-O-HYDROXYAMIDES AND POLY-O-MERCAPTOAMIDES	SEZI , RECAI
<u>08705446</u>	<u>5922825</u>	150	08/29/1996	PREPARATION OF POLY-O-HYDROXYAMIDES AND POLY O-MERCAPTOAMIDES	SEZI , RECAI
<u>08705099</u>	<u>5807969</u>	150	08/28/1996	PREPARATION OF POLY-O-HYDROXYAMIDES AND POLY O-MERCAPTOAMIDES	SEZI , RECAI
<u>08704064</u>	<u>5973202</u>	150	08/28/1996	PREPARATION OF POLY-O-HYDROXYAMIDES AND POLY O-MERCAPTOAMIDES	SEZI , RECAI
<u>08703754</u>	<u>5760162</u>	150	08/27/1996	PREPARATION OF POLY-O-HYDROXYAMIDES AND POLY-O-MERCAPTOAMIDES	SEZI , RECAI
<u>08666182</u>	<u>5777066</u>	150	06/19/1996	METHOD FOR THE PRODUCTION OF POLY-O-HYDROXYAMIDES	SEZI , RECAI
<u>08666177</u>	<u>5750638</u>	150	06/19/1996	METHOD FOR THE PRODUCTION OF POLY-O-HYDROXYAMIDES	SEZI , RECAI
<u>08434955</u>	<u>5616667</u>	150	05/04/1995	COPOLYMERS	SEZI , RECAI
<u>08121658</u>	Not Issued	166	09/15/1993	PHOTORESIST	SEZI , RECAI
<u>07849802</u>	Not Issued	166	03/11/1992	HIGH RESOLUTION PHOTORESIST	SEZI , RECAI
<u>07812582</u>	<u>5194629</u>	150	12/20/1991	PROCESS FOR PRODUCING N-TERTIARY BUTOXYCARBONYL-MALEINIMIDE	SEZI , RECAI
<u>07811831</u>	Not Issued	166	12/20/1991	MIXED POLYMERS	SEZI , RECAI

<u>07811706</u>	<u>5384220</u>	150	12/20/1991	PRODUCTION OF PHOTOLITHOGRAPHIC STRUCTURES	SEZI , RECAI
<u>07692364</u>	<u>5262283</u>	150	04/26/1991	METHOD FOR PRODUCING A RESIST STRUCTURE	SEZI , RECAI
<u>07556014</u>	<u>5171656</u>	150	07/20/1990	PHOTOSENSITIVE COMPOSITION	SEZI , RECAI
<u>07513965</u>	<u>5234793</u>	150	04/24/1990	METHOD FOR DIMENSIONALLY ACCURATE STRUCTURE TRANSFER IN BILAYER TECHNIQUE WHEREIN A TREATING STEP WITH A BULGING AGENT IS EMPLOYED AFTER DEVELOPMENT	SEZI , RECAI
<u>07513865</u>	Not Issued	166	04/24/1990	DRY-DEVELOPABLE RESIST SYSTEM	SEZI , RECAI
<u>07513832</u>	Not Issued	166	04/24/1990	PHOTOSTRUCTURING METHOD	SEZI , RECAI
<u>07513570</u>	<u>5173393</u>	150	04/24/1990	ETCH-RESISTANT DEEP ULTRAVIOLET RESIST PROCESS HAVING AN AROMATIC TREATING STEP AFTER DEVELOPMENT	SEZI , RECAI
<u>07166436</u>	<u>4812200</u>	150	03/10/1988	METHOD FOR GENERATING RESIST STRUCTURES	SEZI , RECAI

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